# Product End-of-Life Disassembly Instructions

**Product Category:** Monitors and Displays

**Marketing Name / Model**
[List multiple models if applicable.]

HP Z25n 25-inch Narrow Bezel IPS Display

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**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assembly (PCA)</td>
<td>With a surface greater than 10 sq cm I/F Board<em>1, Power Board</em>1, Control Board<em>1, Key Board</em>1</td>
<td>4</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>0</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps panel*1</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>Power board (C651, C652)</td>
<td>2</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>DP cable<em>1, miniDP/DP cable</em>1, USB3.0 Cable<em>1, Power cord</em>1 All are inside monitor carton box</td>
<td>4</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
Components, parts and materials containing refractory ceramic fibers | 0
---|---
Components, parts and materials containing radioactive substances | 0

## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screw driver</td>
<td></td>
</tr>
<tr>
<td>Hexagon Screw Driver</td>
<td></td>
</tr>
<tr>
<td>Diagonal cutting nippers</td>
<td></td>
</tr>
<tr>
<td>Nosed pliers</td>
<td></td>
</tr>
</tbody>
</table>

## 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Use quick release button to separate head and stand.
2. Use tool to release screws and disassemble the rear cover by hand.
3. Remove the LVDS, LED, CTRL FFC cables and separate internal.
4. Use tool to release screws on PCBs. Then tear down the gaskets, and AL tapes on main chassis and separate all connector on PCBs.
5. Use tool to release screws on Bezel and Middle Frame. Then tear down the assy-Bezel, Middle Frame and Panel.
6. Use tool to release screws and separate base.
7. Use tool to release screws and separate base cover.
8. Use tool to release screws and separate VESA from stand.
9. Disassemble the middle cover by hand.
10. Disassemble the front cover and back cover by hand.
11. Use tool to release screws and separate front cover.
12. Use tool to release screws and separate middle BKT.
13. Use tool to release screws and separate constant force springs BKT and constant force springs.
14. Use tool to release screws and separate slider.
15. 

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Step 1 : Use quick release button to separate head and stand.
Step 2: Use tool to release screws and disassemble the rear cover by hand.
Step 3: Remove the LVDS, LED, CTRL FFC cables and separate internal.
Step 4: Use tool to release screws on PCBs. Then tear down the gaskets, and AL tapes on main chassis and separate all connector on PCBs.

Step 5: Use tool to release screws on Bezel and Middle Frame. Then tear down the assy-Bezel, Middle Frame and Panel.
Step 6: Use tool to release screws and separate base
Step 7: Use tool to release screws and separate base cover.

Step 8: Use tool to release screws and separate VESA from stand.
Step 9 : Disassemble the middle cover by hand.

Step 10 : Disassemble the front cover and back cover by hand.
Step 11: Use tool to release screws and separate front cover.

Step 12: Use tool to release screws and separate middle BKT.
Step 13: Use tool to release screws and separate constant force springs BKT and constant force springs.

Step 14: Use tool to release screws and separate slider.